

SOT318-1

plastic quad flat package; 80 leads (lead length 1.95 mm);
body 14 x 20 x 2.7 mm; high stand-off height

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	QFP80
Package type industry code	QFP80
Package style descriptive code	QFP (quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-112
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	2.57	-	2.71	2.87	mm
A ₂	package height	[tbd]	-	2.7	[tbd]	mm
n ₂	actual quantity of termination	-	-	80	-	

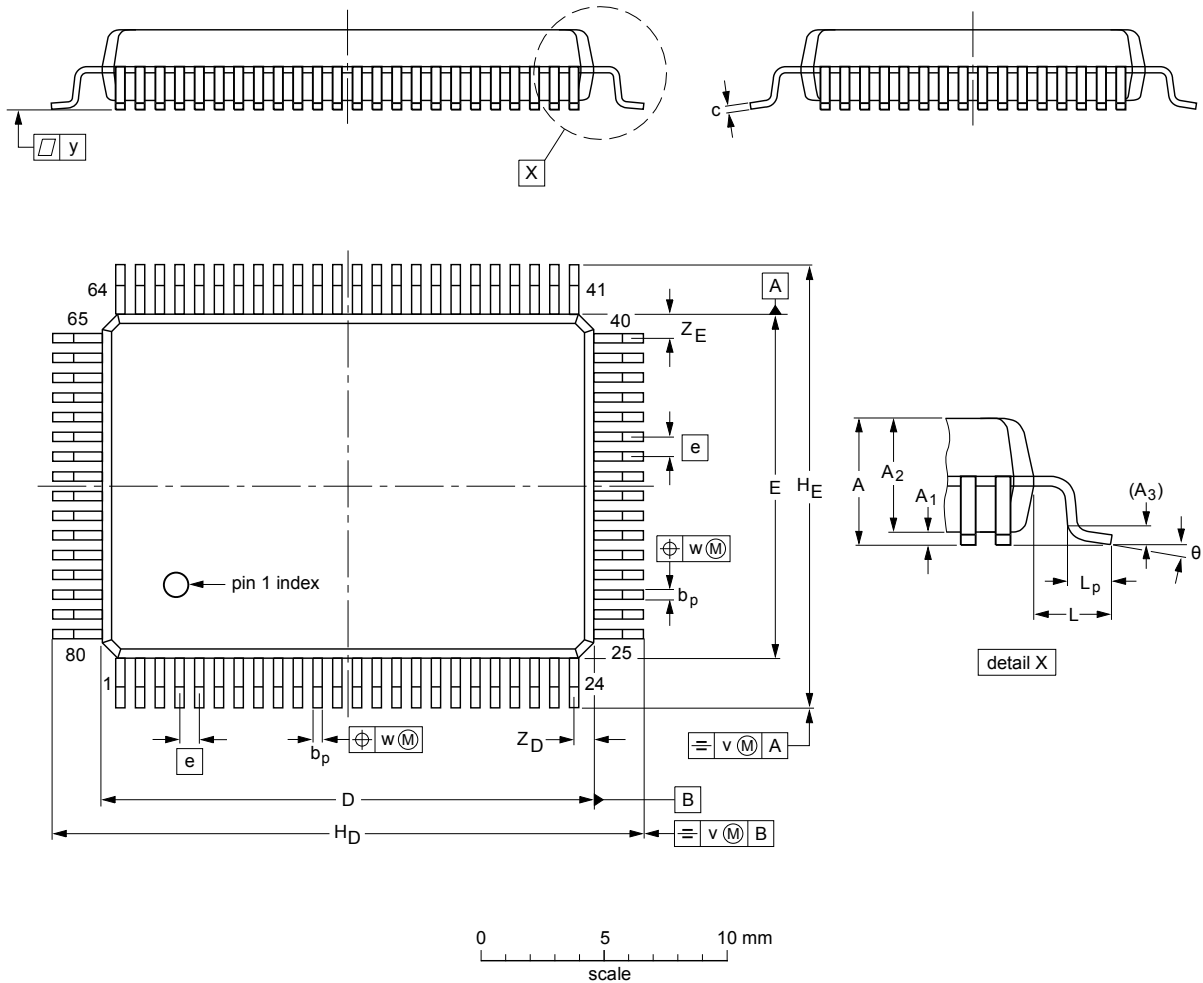


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2. Package outline

QFP80: plastic quad flat package;
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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	3.3	0.36 0.10	2.87 2.57	0.25	0.45 0.30	0.25 0.13	20.1 19.9	14.1 13.9	0.8	24.2 23.6	18.2 17.6	1.95	1.0 0.6	0.2	0.2	0.1	1.0 0.6	1.2 0.8	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT318-1		MO-112			99-12-27 03-02-25

Fig. 1. Package outline QFP80 (SOT318-1)

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3. Soldering

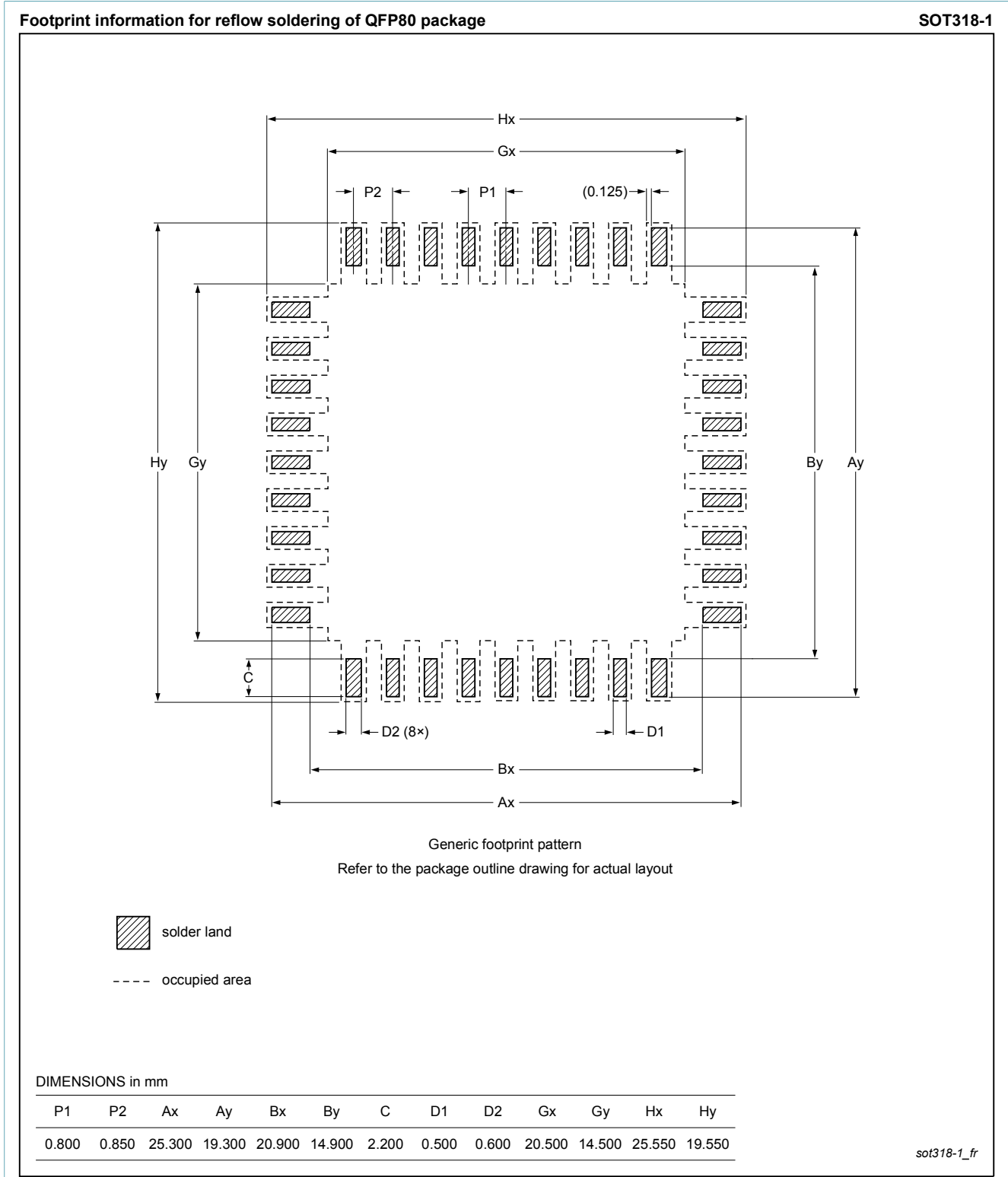
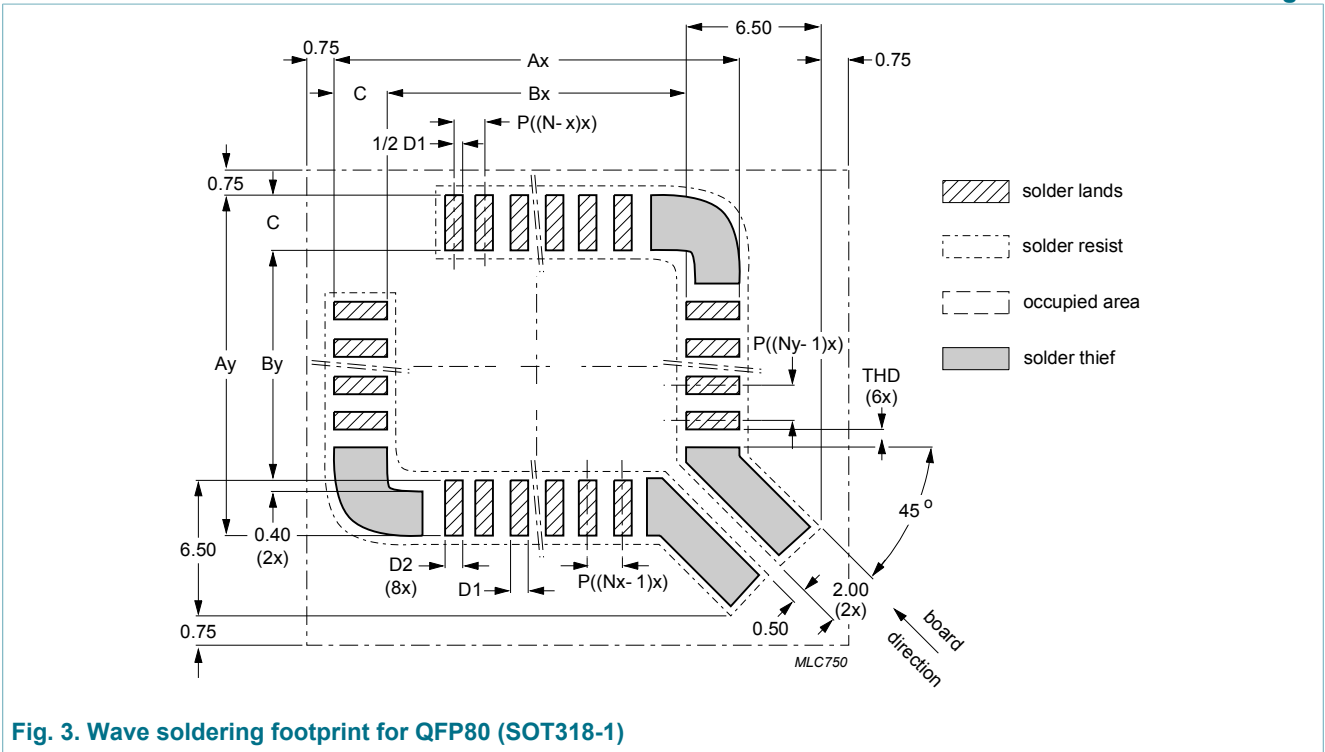


Fig. 2. Reflow soldering footprint for QFP80 (SOT318-1)

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4. Legal information

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